

Lista Lucrari Publicate in Reviste Cotate ISI Web of Science
2013-2020

- 1) *Effect of Local Heating on the Mechanical Characteristics of Repaired Automotive Panels*; Author(s): Navodariu, N; Branzei, M; Ciocoiu, R; Ciuca, I; Coman, R; Raiciu, AD; Semenescu, A; Antoniac, I; Gradinaru, S; Cristescu, I; MATERIALE PLASTICE Volume: 56 Issue: 4 Pages: 750-758; DEC 2019;
- 2) *Fractography Study of Explanted Intramedullary Nails*; Author(s): Cristescu, I; Antoniac, I; Branzei, M; Ghiban, B; Ciocoiu, R; Ciuca, I; Semenescu, A; Gradinaru, S; Pop, D; Raiciu, AD; MATERIALE PLASTICE Volume: 56 Issue: 4 Pages: 759-773; DEC 2019;
- 3) *The Influence of Thermal Shocks on the Thermophysical Properties of the Zircaloy-4*; Anghel, DC; Rosu, AE; Neacsu, G; Popa, IA; Branzei, M; Rizea, V; Ducu, CM; Dicu, MM; Rizea, AD; Ungureanu, E; Abrudeanu, M; REVISTA DE CHIMIE Volume: 70 Issue: 2 Pages: 575-577; FEB 2019;
- 4) *Non-Toxic Environment for Ferritic Nitrocarburising Process*; Author(s): Branzei, M; Cojocaru, MO; Druga, LN Tudose, F; Trusca, R; REVISTA DE CHIMIE Volume: 69 Issue: 9 Pages: 2416-2419; SEP 2018;
- 5) *A New Robust Top-Down Method for Measurement Uncertainty Estimation of the ED (P) - XRFs Outcomes Carried on a Fluorescence Glass*; Author(s): Pencea, I; Branzei, M; Cojocaru, MO; Turcu, RN; Predescu, C; Berbecaru, A; Arges, AP; Comanescu, B; REVISTA DE CHIMIE Volume: 69 Issue: 9 Pages: 2487-2493; SEP 2018;
- 6) *Pack-Aliting in Thermic Powder Mixture Obtained by Mechanical Alloying*; Author(s): Branzei, M; Druga, LN; Tudose, F; Trusca, R; Cojocaru, MO; REVISTA DE CHIMIE Volume: 69 Issue: 8 Pages: 2092-2096; AUG 2018;
- 7) *The Influence of the High Temperatures Thermal Shocks on the Microstructure and Harness of Zircaloy-4 alloy*; Author(s): Popa, IA; Rosu, AE; Neacsu, G; Anghel, DC; Rizea, V; Branzei, M; Ducu, CM; Dicu, MM; Abrudeanu, M (Abrudeanu, Marioara); REVISTA DE CHIMIE Volume: 69 Issue: 7 Pages: 1655-1660; JUL 2018;
- 8) *New Approach for Chemical Homogeneity Analysis of an AISI 316L Stainless Steel Bar Batch*; Author(s): Pencea, I; Branzei, M; Turcu, RN; Sfat, CE; REVISTA DE CHIMIE Volume: 69 Issue: 5 Pages: 1079-1083; MAY 2018;
- 9) *Thermal Cycling Influence on the Transformation Characteristics of a Ni50Ti48Nb2 Shape Memory Alloy*; Gherghescu, IA; Ciuca, S; Jicmon, GL; Dumitrescu, RE; Branzei, M; REVISTA DE CHIMIE Volume: 68 Issue: 5 Pages: 991-996; MAY 2017;
- 10) *Influence of high temperature exposure on the adhesion of a micro-composite refractory enamel to a Ni-18Cr-12W superalloy*; Author(s): Branzei, M; Pencea, I; Matei, AA; Sfat, CE; Antoniac, IV; Turcu, RN; Manoliu, V; JOURNAL OF ADHESION SCIENCE AND TECHNOLOGY Volume: 31 Issue: 23 Pages: 2555-2570 DOI: 10.1080/01694243.2017.1310172; 2017;
- 11) *Influence of Aging Parameters on the Corrosion Resistance of a Biocompatible Ni_{50.6}Ti_{49.4} Shape Memory Alloy*; Author(s): Gherghescu, IA; Jicmon, GL (Jicmon, Gabriela Liliana); Cotrut, C; Branzei, M; Berbecaru, AC; Predescu, AM; Ciuca, S; REVISTA DE CHIMIE Volume: 67 Issue: 9 Pages: 1734-1738; SEP 2016;
- 12) *Solder Joints Quality Assessment as Function of VPS Process Parameters*; Author(s): Branzei, M (Branzei, Mihai); Gherghescu, IA; Ciuca, S; REVISTA DE CHIMIE Volume: 67 Issue: 6 Pages: 1068-1072; JUN 2016;
- 13) *Osseointegration of sputtered SiC-added hydroxyapatite for orthopaedic applications*; Author(s): Vranceanu, DM; Cotrut, CM; Bramowicz, M; Titorencu, I; Kulesza, S; Kiss, A; Berbecaru, A; Pruna, V; Branzei, M; Vladescu, A; CERAMICS INTERNATIONAL Volume: 42 Issue: 8 Pages: 10085-10093 DOI: 10.1016/j.ceramint.2016.03.114; JUN 2016;
- 14) *On Widening the Application Field of a Ti-rich Ni₄₈Ti₅₂ Shape Memory Alloy Through Ageing Conditions*; Author(s): Gherghescu, IA; Jicmon, GL; Branzei, M; Tarcolea, M; Ciuca, S; REVISTA DE CHIMIE Volume: 67 Issue: 2 Pages: 302-307; FEB 2016;
- 15) *Corrosion resistance appraisal of TiN, TiCN and TiAlN coatings deposited by CAE-PVD method on WC-Co cutting tools exposed to artificial sea water*; Author(s): Matei, AA; Pencea, I; Branzei, M; Tranca, DE; Tepes, G; Sfat, CE; Ciovetica, E; Gherghilescu, AI; Stanciu, GA; APPLIED SURFACE SCIENCE Volume: 358 Pages: 572-578; DEC 2015;
- 16) *Study on laser welding of AISI 316L austenitic stainless steel*; Author(s): Dontu, O; Moreno, JLO; Ciobanu, R; Branzei, M; Besnea, D; JOURNAL OF OPTOELECTRONICS AND ADVANCED MATERIALS Volume: 17 Issue: 9-10 Pages: 1444-1449; SEP-OCT 2015;
- 17) *Hydroxyapatite induced microstructure by cooling rate modification of cancellous bone thermal treatment*; Author(s): Miculescu, F; Purcaru, A; Miculescu, M; Ciocan, LT; Voicu, SI; Maidaniuc, A; Mocanu, A; Branzei, M; JOURNAL OF OPTOELECTRONICS AND ADVANCED MATERIALS Volume: 17 Issue: 7-8 Pages: 1219-1224; JUL-AUG 2015;
- 18) *Thermal processing temperature influence on hard tissue chemical composition*; Author(s): Miculescu, F; Ciocan, LT; Miculescu, M; Branzei, M; Ghiban, N; JOURNAL OF OPTOELECTRONICS AND ADVANCED MATERIALS Volume: 15 Issue: 7-8 Pages: 707-711; JUL-AUG 2013;
- 19) *Preliminary Study Concerning the Role of the Thermo-Physical Factors During the Heating Process of the Heavy Ingots for Forging*; Author(s): Constantinescu, D; Berbecaru, A; Branzei, M; Carlan, BA; Coman, G; METALURGIA INTERNATIONAL Volume: 18 Special Issue: 2 Pages: 158-162; 2013.

Lista Lucrari Publicate in Proceedings Indexate ISI Web of Science 2013-2020

- 1) *Mechanical vs. Electrical Properties of Conductive Adhesive Bonds as Function of Operating Temperature*; Author(s): Branzei, M; Svasta, PM; Vladescu, M; Plotog, I; Mihailescu, B; Varzaru, G; IEEE; 2019 42ND INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE Published: 2019;
- 2) *Thermal Investigations on Modules Realized Using Solderless Assembly for Electronics Technology*; Author(s): Ionescu, C; Branzei, M; Codreanu, N; Varzaru, G; IEEE; 2019 42ND INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE Published: 2019;
- 3) *Investigations Related to Electrically Conductive Adhesives Pastes Usage on SMT Lines*; Author(s): Branzei, M; Varzaru, G; Vladescu, M; Mihailescu, B; Plotog, I; IEEE; 2018 IEEE 24TH INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 355-360 Published: 2018;
- 4) *Mechanical properties of LEDs bonds realized with conductive adhesives paste*; Author(s): Branzei, M; Vladescu, M; Plotog, I; Varzaru, G; Mihailescu, B; ADVANCED TOPICS IN OPTOELECTRONICS, MICROELECTRONICS, AND NANOTECHNOLOGIES IX Book Series: Proceedings of SPIE Volume: 10977 Article Number: UNSP 109770I DOI: 10.1117/12.2326206; 2018;
- 5) *Properties Investigations on Copper Based Printed Conductive Pastes Electrical Joints*; Author(s): Branzei, M; Ionescu, C; Plotog, I; Varzaru, G; IEEE; 2018 41ST INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE; 2018;
- 6) *Microstructure Morphology of No-Clean Lead-Free Solder Alloys Used in Automotive Industry*; Author(s): Branzei, M; Plotog, I; Mihailescu, B; Matei, AA; Cucu, TC; IEEE; 2017 IEEE 23RD INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 78-81; 2017;
- 7) *Comparative Shear Tests of Two Low Melting Point Solder Pastes Relating to their Thermal Diffusivity*; Author(s): Branzei, M; Vladescu, M; Plotog, I; Cucu, T; IEEE; 2017 40TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE; 2017;
- 8) *Comparative shear tests of some low temperature lead-free solder pastes*; Author(s): Branzei, M; Plotog, I; Varzaru, G; Cucu, TC; ADVANCED TOPICS IN OPTOELECTRONICS, MICROELECTRONICS, AND NANOTECHNOLOGIES VIII Book Series: Proceedings of SPIE Volume: 10010 Article Number: UNSP 100100J DOI: 10.1117/12.2246106 Published: 2016;
- 9) *Thermophysical properties of some low temperature lead-free solder pastes dedicated to automotive applications*; Author(s): Branzei, M; Plotog, I; Varzaru, G; Cucu, TC; IEEE; 2016 IEEE 22ND INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY AND ELECTRONIC PACKAGING (SIITME) Pages: 44-47; 2016;
- 10) *Typical Defects Caused by Untypical Situations from Assembling Lines Analysis*; Author(s): Branzei, M; Plotog, I; Marginean, B; IEEE; 2015 IEEE 21ST INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 65-70; 2015;
- 11) *Aspects on Thermophysical Properties of Interconnection Structures for Power LEDs Applications*; Author(s): Branzei, M; Vladescu, M; IEEE; 2015 IEEE 21ST INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 83-86; 2015;
- 12) *Shear Strength Function of Temperature for Lead/Lead-Free Alloys Samples Obtained with Different Cooling Rate*; Author(s): Branzei, M; Varzaru, G; Svasta, PM; 2015 38TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE 2015) Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 255-260; 2015;
- 13) *Studies on Thermal Properties of Substrates for Electronics using IR Thermography*; Author(s): Ionescu, C; Branzei, M; Mihailescu, B; Bonfert, D; IEEE; 2014 IEEE 20TH INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 45-49; 2014;
- 14) *Mechanical Tests Regarding Low-Temperature Lead-Free Solder Pastes Application in Automotive Electronics*; Author(s): Cucu, TC; Plotog, I; Branzei, M; IEEE; 2014 IEEE 20TH INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 63-68; 2014;
- 15) *Correlation between Microstructure and Magnetic Properties on MnZn Ferrite with Bi₂O₃ Increasing Addition*; Author(s): Branzei, M; Cristea, I; Ciuca, I; Bibis, A; Feder, M; ADVANCED MATERIALS AND STRUCTURES V Book Series: Solid State Phenomena Volume: 216 Pages: 23-28; 2014;
- 16) *Implant surface finishing influence on tissue-implant anchoring*; Author(s): Miculescu, F; Ciocan, LT; Miculescu, M; Meghea, D; Bane, M; Branzei, M; ADVANCED MATERIALS AND STRUCTURES V Book Series: Solid State Phenomena Volume: 216 Pages: 39-44; 2014;
- 17) *A study on metal-ceramic thermal expansion compatibility*; Author(s): Miculescu, M; Branzei, M; Miculescu, F; Meghea, D; Bane, M; ADVANCED MATERIALS AND STRUCTURES V Book Series: Solid State Phenomena Volume: 216 Pages: 85-90; 2014;
- 18) *Investigation on Thermal Properties of Substrates for Printed Electronics*; Author(s): Ionescu, C; Bonfert, D; Branzei, M; PROCEEDINGS OF THE 2014 37TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) - ADVANCES IN ELECTRONIC SYSTEM INTEGRATION Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 75-80; 2014;
- 19) *Lead/Lead-Free Solder Alloys Shear Tests Correlations with Structure at Different Temperatures*; Author(s): Branzei, M; Mihailescu, B; Pencea, I; PROCEEDINGS OF THE 2014 37TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) - ADVANCES IN ELECTRONIC SYSTEM INTEGRATION Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 256-259; 2014;
- 20) *Lead/Lead Free Solder Joints Comparative Electrical Tests as Function of Microstructure and Soldering Thermal Profile*; Author(s): Branzei, M; Miculescu, F; Bibis, A; Cristea, I; Plotog, I; Varzaru, G; Mihailescu, B; IEEE; 2013

- IEEE 19TH INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 255-258; 2013;
- 21) *Lead/Lead Free Solder Joints Comparative Shear Tests Function of Working Temperature and Soldering Thermal Profile*; Author(s): Plotog, I; Varzaru, G; Mihailescu, B; Branzei, M; Bibis, A; Cristea, I; IEEE; 2013 IEEE 19TH INTERNATIONAL SYMPOSIUM FOR DESIGN AND TECHNOLOGY IN ELECTRONIC PACKAGING (SIITME) Book Series: International Symposium for Design and Technology in Electronic Packaging Pages: 283-286; 2013;
 - 22) *The Mischmetal and Bi94Zn6 Effect Alloying on SACX 0307*; Author(s): Branzei, M; Pencea, I; Plotog, I; Miculescu, F; Cristea, I; Thumm, A; IEEE; 2013 PROCEEDINGS OF THE 36TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 24-29; 2013;
 - 23) *Multiconvolutional Approach for Uncertainty Estimation of the Thermal Diffusivity Measured by Flash Method*; Author(s): Pencea, I; Plotog, I; Branzei, M; Bibis, A; Svasta, P; IEEE; 2013 PROCEEDINGS OF THE 36TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE) Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 195-201; 2013;
 - 24) *Complex Characterization of a New Low Ni Maraging Steel with Enhance Service Stability*; Author(s): Branzei, M; Nedelcu, I; Miculescu, M; ADVANCED MATERIALS AND STRUCTURES IV Book Series: Solid State Phenomena Volume: 188 Pages: 346-352; 2012;
 - 25) *Solder Joints Properties as Function of Multiple Reflow Vapor Phase Soldering Process*; Author(s): Branzei, M; Plotog, I; Miculescu, F; Varzaru, G; Svasta, P; Thumm, A; IEEE; 2012 35TH INTERNATIONAL SPRING SEMINAR ON ELECTRONICS TECHNOLOGY (ISSE 2012): POWER ELECTRONICS Book Series: International Spring Seminar on Electronics Technology ISSE Pages: 155-160; 2012.